L Number	Hits	Search Text	DB	Time stamp
1	64234		USPAT;	2004/08/10 09:47
1			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
2	1215		IBM_TDB USPAT;	2004/08/10 09:47
4	1315	pressure adj sensitive adj paper	US-PGPUB;	2004/00/10 09.47
			EPO; JPO;	
			DERWENT;	
1			IBM_TDB	
3	1	, , (F)	USPAT;	2004/08/10 09:46
		adj paper)	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
4	32466	451/\$.ccls.	USOCR	2004/08/10 09:47
5	113	pressure adj sensitive adj paper	USOCR	2004/08/10 09:47
6	0	451/\$.ccls. and (pressure adj sensitive	USOCR	2004/08/10 09:47
		adj paper)		
10	3275840	condition conditioner conditioning	USPAT;	2004/08/10 09:49
		conditions conditioners conditioned	US-PGPUB; EPO; JPO;	
			DERWENT;	
:			IBM TDB	
11	2709203	wafer wafers substrate substrates	USPĀT;	2004/08/10 09:49
]		semiconductor semiconductors	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
12	2021902	sensor sensors sensing sense sensed senses	USPAT;	2004/08/10 09:49
	2022302		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	10077	/ N	IBM_TDB	2004/00/10 10-11
13	10377	(condition conditioner conditioning conditions conditioners conditioned) same	USPAT; US-PGPUB;	2004/08/10 10:11
		(wafer wafers substrate substrates	EPO; JPO;	
		semiconductor semiconductors) same (sensor	DERWENT;	
		sensors sensing sense sensed senses)	IBM_TDB	
14	3212959	pressure pressures	USPAT;	2004/08/10 09:50
			US-PGPUB;	
			EPO; JPO; DERWENT;	
[IBM TDB	
15	296272	database databases (data adj (base bases))	USPAT;	2004/08/10 09:51
	-		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
16	2	((condition conditioner conditioning	USPAT;	2004/08/10 09:53
- ~	۷	conditions conditioners conditioned) same	US-PGPUB;	-551, 55, 15 65.55
		(wafer wafers substrate substrates	EPO; JPO;	
		semiconductor semiconductors) same (sensor	DERWENT;	
		sensors sensing sense sensed senses))	IBM_TDB	
		same (pressure pressures) same (database databases (data adj (base bases)))		
17	14		USPAT;	2004/08/10 09:54
* '	7.4	conditions conditioners conditioned) same	US-PGPUB;	-551, 55, 15 55.51
		(wafer wafers substrate substrates	EPO; JPO;	
		semiconductor semiconductors) same (sensor	DERWENT;	
		sensors sensing sense sensed senses)) and	IBM_TDB	
		((pressure pressures) with (database databases (data adj (base bases))))		
18	247	451/\$.ccls. and ((condition conditioner	USPAT;	2004/08/10 09:58
		conditioning conditions conditioners	US-PGPUB;	
		conditioned) same (wafer wafers substrate	EPO; JPO;	
		substrates semiconductor semiconductors)	DERWENT;	
		same (sensor sensors sensing sense sensed	IBM_TDB	
		senses))	l	L

19 63 (451/\$.ccls. and ((condition conditioner conditioning conditions conditioners conditioners conditioned) same (wafer wafers substrate substrates semiconductor semiconductors) Substrates semiconductor semiconductors) DERWENT	2004/08/10 10:01
conditioned) same (wafer wafers substrate EPO; JI substrates semiconductor semiconductors) DERWENT	IB: I
substrates semiconductor semiconductors) DERWENT	
) · · · · · · · · · · · · · · · · · · ·	·
same (sensor sensors sensing sense sensed IBM TDF	
senses))) and conditioner	
0 ((451/\$.ccls. and ((condition conditioner USPAT;	2004/08/10 09:59
conditioning conditions conditioners US-PGPU conditioned) same (wafer wafers substrate EPO; J	· ·
conditioned) same (wafer wafers substrate EPO; JE substrates semiconductor semiconductors) DERWENT	· · · · · · · · · · · · · · · · · · ·
same (sensor sensors sensing sense sensed IBM TDE	· •
senses))) and conditioner) and (pressure	
adj sensitive adj paper)	
21 2894295 determine determining determines USPAT;	2004/08/10 10:02
determined US-PGPU EPO; JI	
DERWENT	
IBM TDE	
22 4118120 (sensor sensors sensing sense sensed USPAT;	2004/08/10 10:03
senses) or (determine determining US-PGPU	· 1
determines determined) EPO; JI	
DERWENT	· ·
23 42 (pressure adj sensitive adj paper) with USPAT;	2004/08/10 10:07
((sensor sensors sensing sense sensed US-PGPU	JB;
senses) or (determine determining EPO; JR	
determines determined)) DERWENT	
IBM_TDE 24	2004/08/10 10:07
sensed senses) or (determine determining US-PGPU	1
determines determined)) with (pressure adj EPO; JE	· ·
sensitive adj paper) DERWENT	· .
IBM_TDE	
25 3 (condition conditioner conditioning USPAT; conditions conditioners conditioned) with US-PGPU	2004/08/10 10:10
((sensor sensors sensing sense sensed EPO; JI	
senses) or (determine determining DERWENT	
determines determined)) with (pressure adj IBM_TDE	3
sensitive adj paper)	
3 ((condition conditioner conditioning USPAT; conditions conditioners conditioned) with US-PGPU	2004/08/10 10:11
(pressure adj sensitive adj paper)) same EPO; JE	-
((sensor sensors sensing sense sensed DERWENT	
senses) or (determine determining IBM_TDE	3
determines determined))	0004/00/10 10 10
27 3023 (condition conditioner conditioning USPAT; conditions conditioners conditioned) with US-PGPU	2004/08/10 10:13
(wafer wafers substrate substrates EPO; JF	· ·
semiconductor semiconductors) with (sensor DERWENT	
sensors sensing sense sensed senses) IBM_TDM	3
0 ((condition conditioner conditioning USPAT;	2004/08/10 10:13
conditions conditioners conditioned) with US-PGPC (wafer wafers substrate substrates EPO; JE	
(warer warers substrate substrates EPO; Je semiconductor semiconductors) with (sensor DERWENT	
sensors sensing sense sensed senses)) and IBM TDE	
(pressure adj sensitive adj paper)	
29 167 ((condition conditioner conditioning USPAT;	2004/08/10 10:13
conditions conditioners conditioned) with US-PGPU (wafer wafers substrate substrates EPO; JE	
semiconductor semiconductors) with (sensor DERWENT	
sensors sensing sense sensed senses)) IBM_TDM	
with conditioner	
30 3 (((condition conditioner conditioning USPAT;	2004/08/10 10:15
conditions conditioners conditioned) with US-PGPU (wafer wafers substrate substrates EPO; JE	* 1
semiconductor semiconductors) with (sensor DERWENT	•
sensors sensing sense sensed senses)) IBM_TDE	
with conditioner) and 451/\$.ccls.	·

31	749	(polishing adj pad) with conditioner	USPAT; US-PGPUB; EPO; JPO;	2004/08/10 10:15
			DERWENT; IBM_TDB	
32	0	(pressure adj sensitive adj paper) and ((polishing adj pad) with conditioner)	USPĀT; US-PGPUB; EPO; JPO;	2004/08/10 10:15
33	25		DERWENT; IBM_TDB USPAT;	2004/08/10 10:16
33	25	conditions conditioners conditioned) with (wafer wafers substrate substrates semiconductor semiconductors) with (sensor	US-PGPUB; EPO; JPO; DERWENT;	2004/08/10 10:16
34	71653	sensors sensing sense sensed senses)) and ((polishing adj pad) with conditioner) (uniformity uniform) with (pressure pressures)	IBM_TDB USPAT; US-PGPUB;	2004/08/10 10:17
		pressures	EPO; JPO; DERWENT; IBM TDB	
35	292	((uniformity uniform) with (pressure pressures)) and ((condition conditioner conditioning conditions conditioners	USPAT; US-PGPUB; EPO; JPO;	2004/08/10 10:17
		conditioned) same (wafer wafers substrate substrates semiconductor semiconductors) same (sensor sensors sensing sense sensed	DERWENT; IBM_TDB	
36	71653	senses)) ((uniformity uniform) with (pressure pressures)) samel13	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/08/10 10:17
37	44	((uniformity uniform) with (pressure pressures)) same ((condition conditioner conditioning conditions conditioners conditioned) same (wafer wafers substrate substrates semiconductor semiconductors)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/10 10:19
38	0	same (sensor sensors sensing sense sensed senses)) uniformity near3 pressure near3	USPAT;	2004/08/10 10:19
		conditioner	US-PGPUB; EPO; JPO; DERWENT;	
39	0	uniformity near5 pressure near5 conditioner	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/08/10 10:20
			DERWENT; IBM_TDB	
40	0	(uniformity adj3 pressure) near5 conditioner	USPAT; US-PGPUB; EPO; JPO;	2004/08/10 10:20
41	1682	(uniformity adj3 pressure)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/08/10 10:20
43	11	(((uniformity adj3 pressure)) and conditioner) and polishing	DERWENT; IBM_TDB USPAT; US-PGPUB;	2004/08/10 10:20
		, <u>.</u>	EPO; JPO; DERWENT; IBM TDB	
42	48	((uniformity adj3 pressure)) and conditioner	USPAT; US-PGPUB; EPO; JPO;	2004/08/10 10:35
			DERWENT; IBM_TDB	

44	11	((polishing adj pad) with conditioner)	USPAT;	2004/08/10 10:58
		with ((uniformity uniform) with (pressure	US-PGPUB;	
		pressures))	EPO; JPO;	
			DERWENT;	
			IBM TDB	
45	4	"6477447"	USPĀT;	2004/08/10 10:59
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	